

## ABSTRACT OF THE DISCLOSURE:

TITLE: SYSTEM FOR TESTING ONE OR MORE GROUPS OF  
IC-CHIPS WHILE CONCURRENTLY LOADING/UNLOADING  
ANOTHER GROUP

An electromechanical system for testing IC-chips includes a total of  $N$  chip holding subassemblies, where  $N$  is an integer greater than one and where each chip holding subassembly has sockets for holding a group  
5 of IC-modules that include the IC-chips; a moving mechanism for automatically moving the  $i$ -th chip holding subassembly from a load position in the system to a test position in the system, and visa-versa, where  $i$  ranges from 1 to  $N$  and changes with time in a sequence; and a  
10 temperature control mechanism which contacts the IC-modules at the test position. Between the moving of the  $i$ -th chip holding subassembly and the next chip holding subassembly in the sequence, the IC-chips are  
15 burn-in tested on all  $N$  of the chip holding subassemblies. Also, while the  $i$ -th chip holding subassembly is being moved, burn-in testing of IC-chips on the remaining  $N-1$  chip holding subassemblies continues.